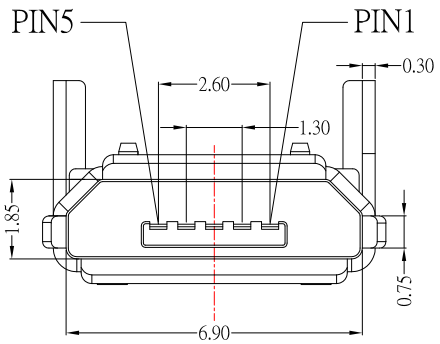
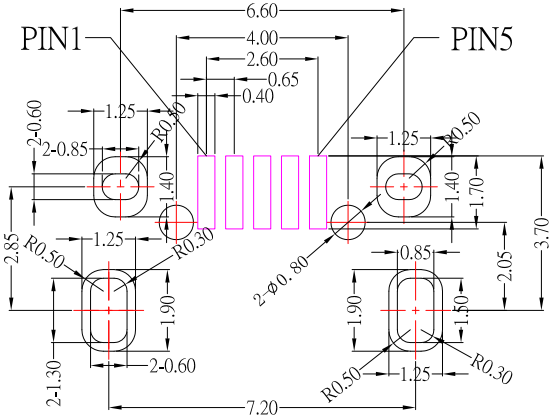
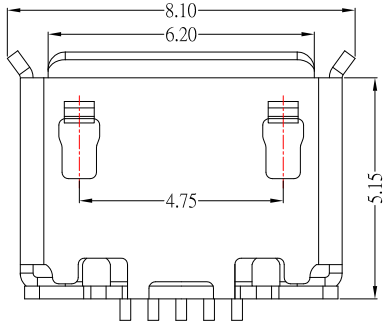
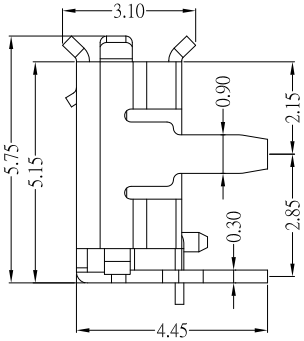
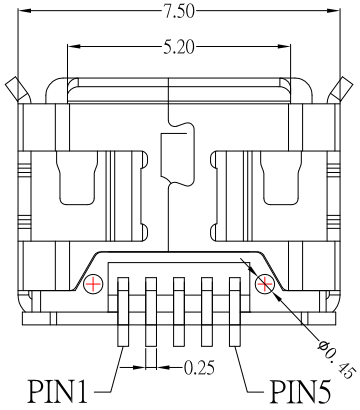


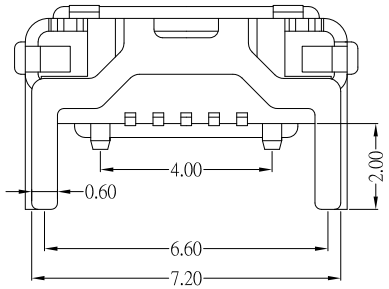




RECOMMENDED PCB LAYOUT




## SPECIFICATIONS

**Electrical:**

1.Current Rating: 1.0A

2.Voltage Rating: 30V

3.Contact Resistance: 30 mΩ Max

4.Dielectric Withstanding Voltage: 100 V AC Min

5.Insulation Resistance: 100 MΩ Min

**Mechanical:**

1.Connector Mate and Unmate Force

1.1 Mate force: 35N (Max)

1.2 Unmate force: 10N(Min)

**Material:**

1.Housing: LCP

2.Contact: Brass

3.Shell: SUS

Finish:

1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls
Nickel under plated overall

2.Shell: Nickel under Plated surface layer

| ITEM NO. | DESCRIPTION | DRAWN | DATE |
|---|---|---|---|
| 8 | 新增尺寸 | Jack | 071520 |
| 7 | 新增PIN標示 | Jack | 121917 |
| 6 | 更新為A0版 | Jack | 022316 |
| 5 | 更新PCB LAYOUT圖樣式 | Jack | 041715 |
| 4 | 更新圖面尺寸 | Jack | 111214 |
| 3 | 更新為A0版 | Jack | 102814 |
| 2 | 更新尺寸3.80改4.00 | Jack | 100214 |
| 1 | 更新尺寸4.00改3.80及2.88改2.80及<br>更新pcb layout尺寸 | Jack | 100114 |
| 10 | 更新PCB LAYOUT尺寸 | Jack | 031523 |
| 9 | 更新底部樣式 | Jack | 112822 |

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S | UNITS MM

| | | | |
|---|---|---|---|
| DRAWN BY: Jack Lu | DATE 03/15/23 | MAT'L | |
| CHECKED BY: Jacky Chen | DATE 03/15/23 | FINISH | |
| APPROVED BY: Tony Kao | DATE 03/15/23 | SCALE 1 : 1 | SHEET NO. 1 of 1 |

| | | | |
|---|---|---|---|
| TITLE | CONNECTOR | | |
| MODLE | MICRO USB BF CONNECTOR | | |
| DWG NO. | MRUSB-5B-EDA-S129 | SIZE | A4 |
| PART NO. | MRUSB-5B-EDA-S129 | VER | R10 |